Operating Operating -35°C to +85°C (Notes 1) Bitmage Interpetute range operating -10°C to +60°C (Note3) Rating Operating Operating 20 % to 30 % (Notes 2) Bitmage Introduly mage 40 % to 70 % (Note3) Voltage 150 V AC (DC) Current 1 A packable Contact DF13 (G)-26303CF Image: DF13 (G)-26303CF DF13 (G)-26303CF DF13 (G)-26303CF Construction Specifications [QT [A Construction General examination [Visually and by measuring instrument. According to drawing. X X Raking proof 500 V AC for 1 min. No flashover or breakdown. X X Voltage proof 500 V AC for 1 min. No flashover or breakdown. X X Woration 30 mines insertions and extractions. ID contact resistance: 30 mi2 MAX. X X Vibration Prequency 10 to 55 Hz, single amplitude ID contact resistance: 30 mi2 MAX. X X X Vibration Prequency 10 to 55 Hz, single amplitude ID contact resistance: 30 mi2 MAX. X X X X X X	Applicable	e standard									
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